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FIG. 1

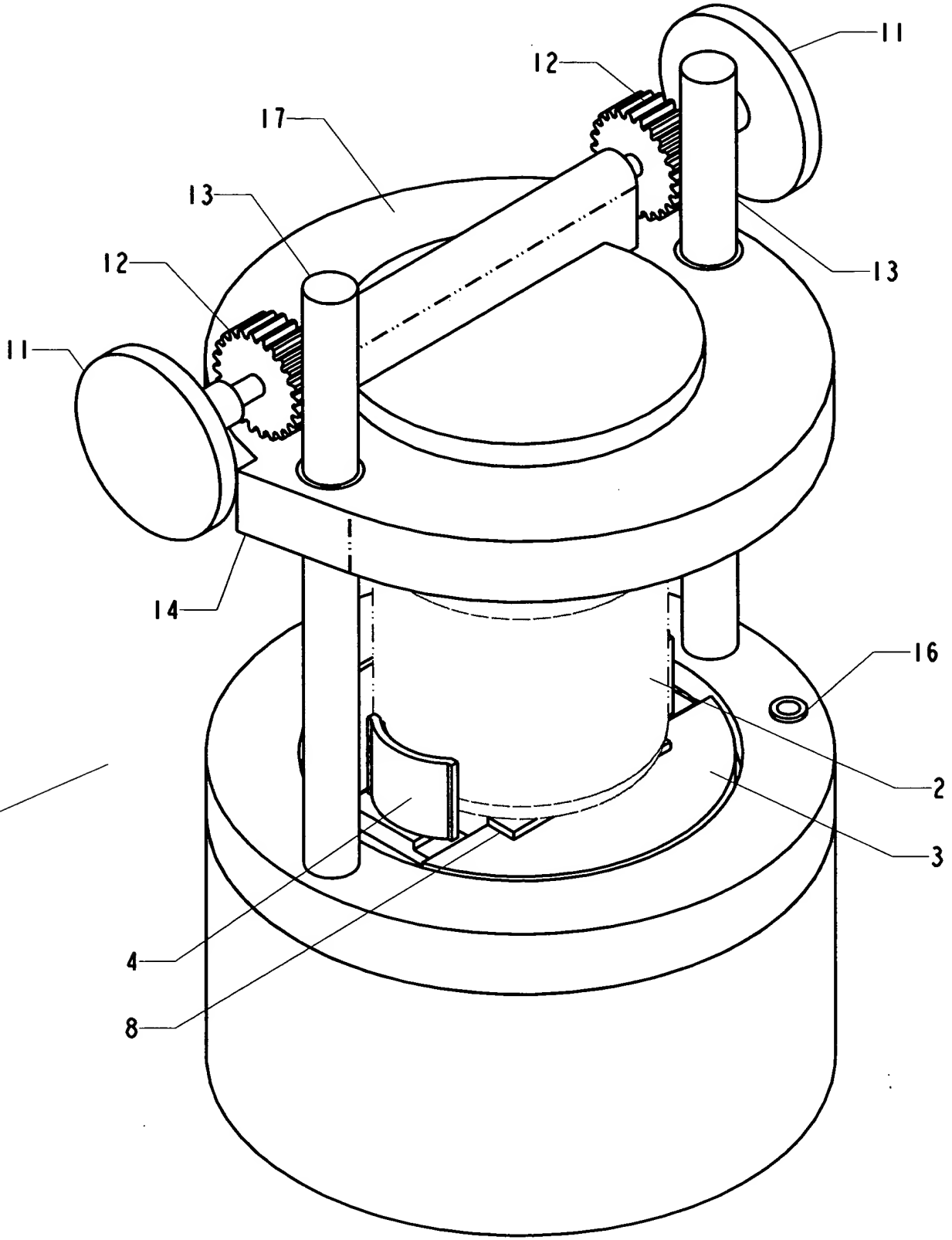


Figure 1

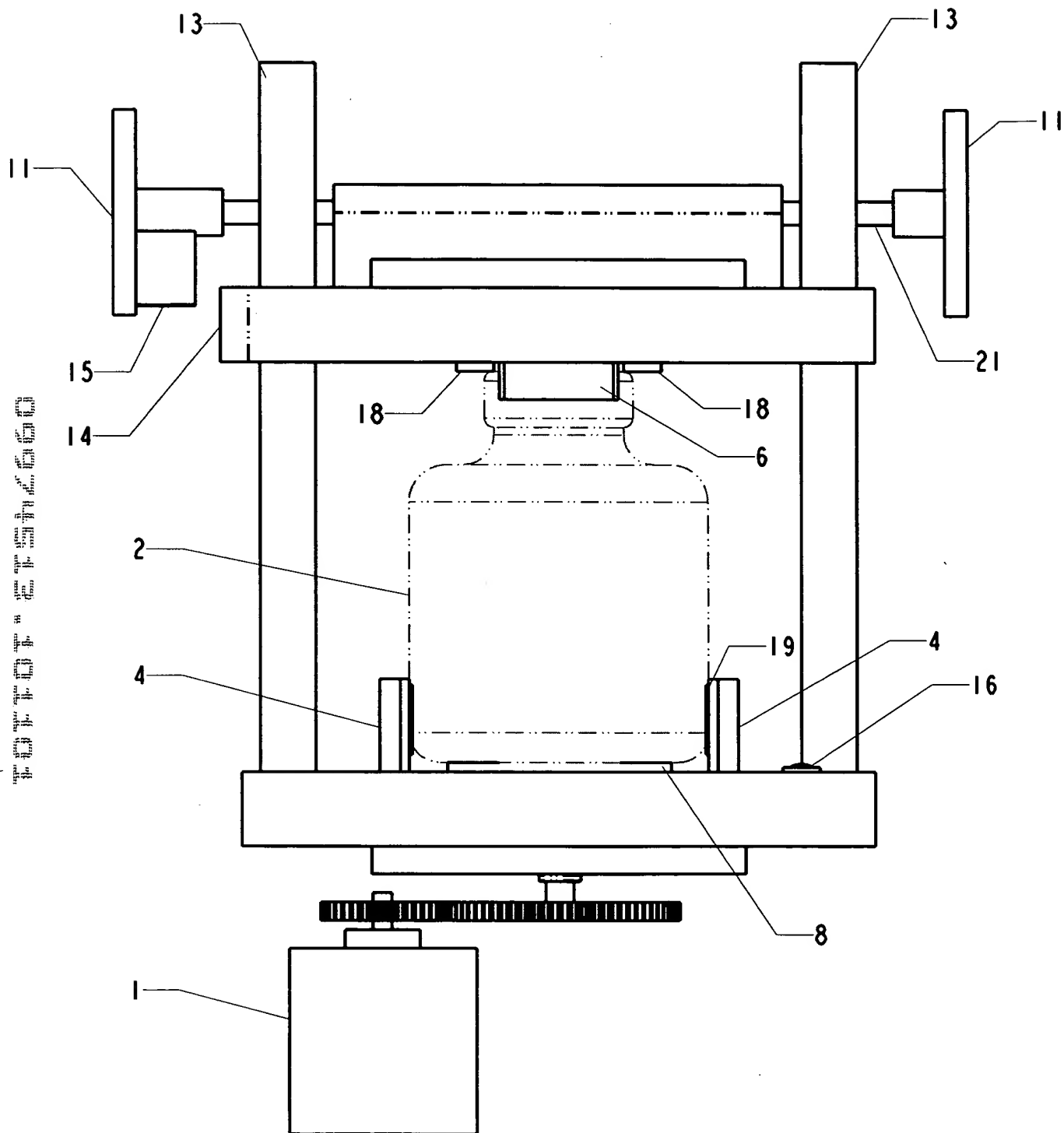


Figure 2

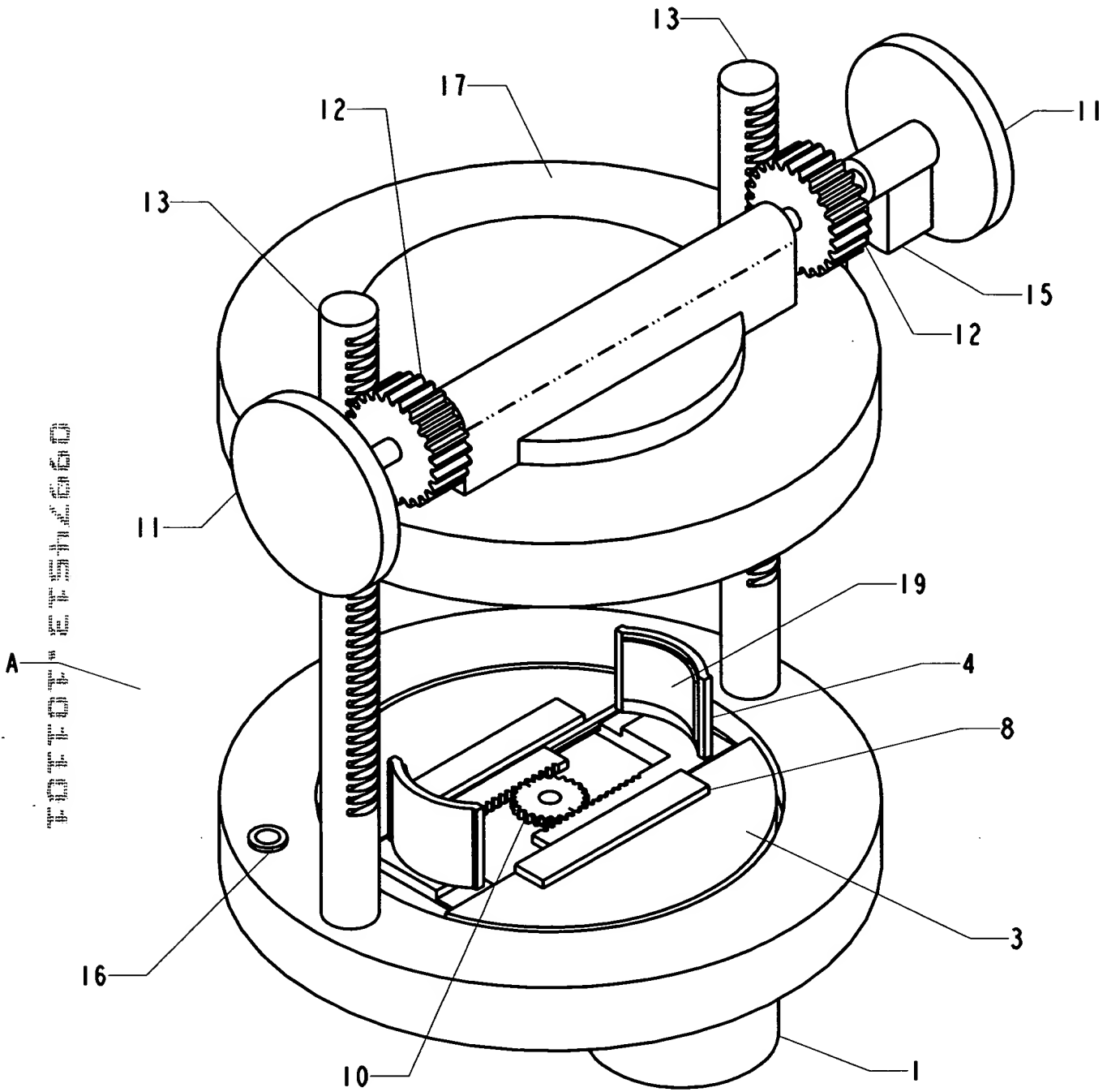


Figure 3

FIG. 4

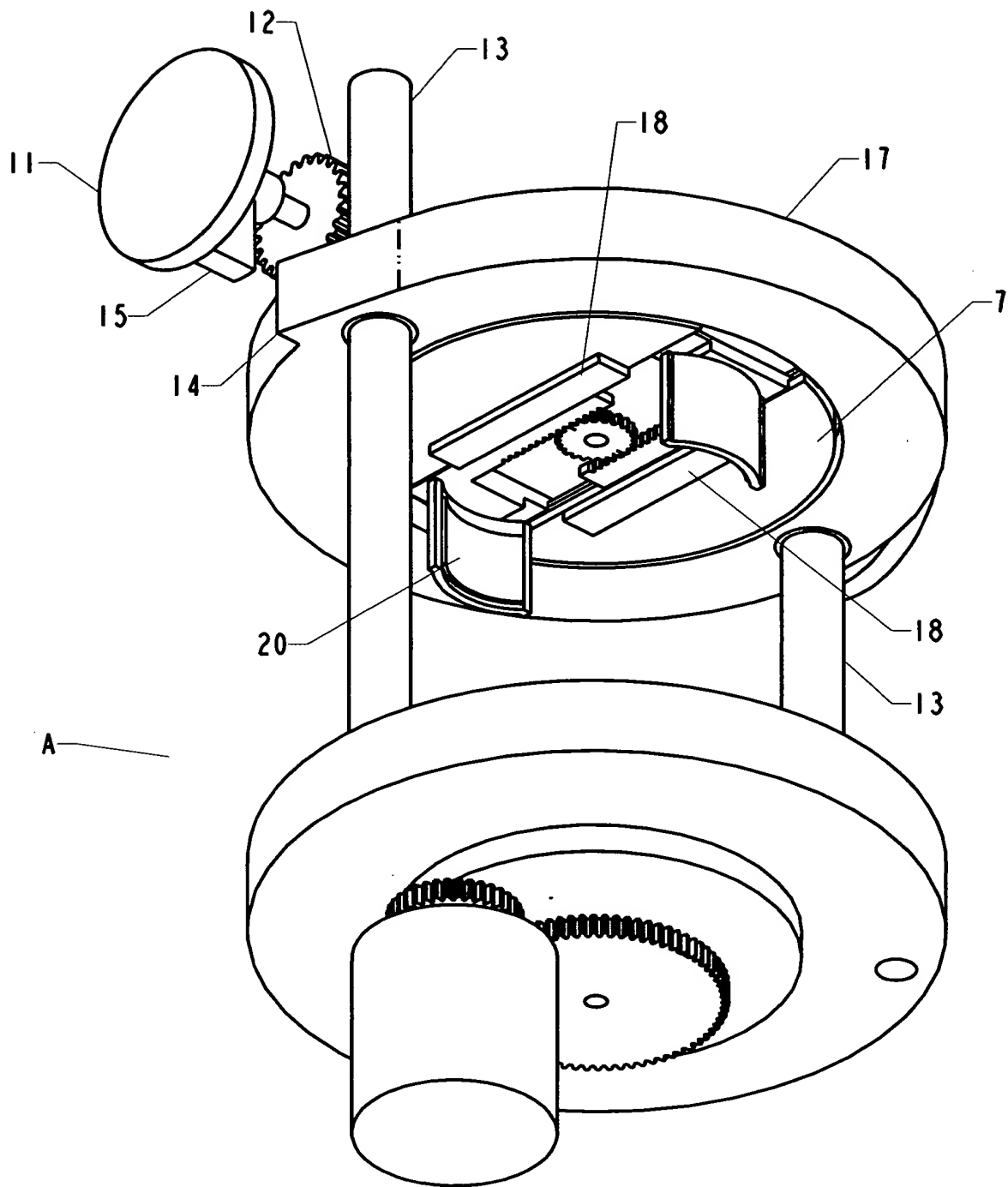


Figure 4

This cross-sectional diagram illustrates a complex multi-layered assembly, likely a printed circuit board or a semiconductor package. The assembly is composed of several distinct layers and components, each identified by a numerical label:

- 3**: A top layer or substrate material, shown with diagonal hatching.
- 4**: A rectangular component or layer situated below the top layer.
- 8**: A central layer or component, also shown with diagonal hatching.
- 9**: A layer or component located between the central layer and the bottom layer.
- 10**: A layer or component located between the central layer and the bottom layer.
- 13**: A large, rectangular component or layer, possibly a heat sink or a protective cover, positioned on the left side.
- 16**: A small, circular component or feature located on the top layer.
- 19**: A small, rectangular component or feature located on the top layer.

The assembly is shown in a cross-sectional view, revealing the internal structure and the relationship between the various layers and components. The hatching pattern is used to distinguish between different materials or layers.

Figure 5

[illegible]

Figure 6